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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	6144
Number of Logic Elements/Cells	27648
Total RAM Bits	393216
Number of I/O	158
Number of Gates	1569178
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	240-BFQFP Exposed Pad
Supplier Device Package	240-PQFP (32x32)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xcv1000e-8hq240c

Dedicated Routing

Some classes of signal require dedicated routing resources to maximize performance. In the Virtex-E architecture, dedicated routing resources are provided for two classes of signal.

- Horizontal routing resources are provided for on-chip 3-state buses. Four partitionable bus lines are provided per CLB row, permitting multiple buses within a row, as shown in Figure 8.
- Two dedicated nets per CLB propagate carry signals vertically to the adjacent CLB.Global Clock Distribution Network
- DLL Location

Clock Routing

Clock Routing resources distribute clocks and other signals with very high fanout throughout the device. Virtex-E devices include two tiers of clock routing resources referred to as global and local clock routing resources.

- The global routing resources are four dedicated global nets with dedicated input pins that are designed to distribute high-fanout clock signals with minimal skew. Each global clock net can drive all CLB, IOB, and block RAM clock pins. The global nets can be driven only by global buffers. There are four global buffers, one for each global net.
- The local clock routing resources consist of 24 backbone lines, 12 across the top of the chip and 12 across bottom. From these lines, up to 12 unique signals per column can be distributed via the 12 longlines in the column. These local resources are more flexible than the global resources since they are not restricted to routing only to clock pins.

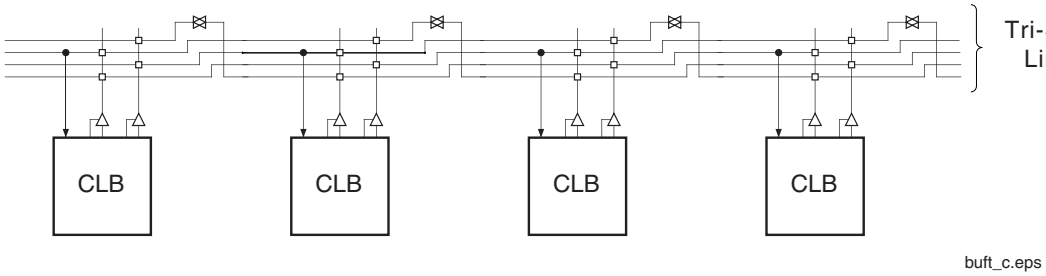

Figure 8: **BUFT Connections to Dedicated Horizontal Bus LInes**

Global Clock Distribution

Virtex-E provides high-speed, low-skew clock distribution through the global routing resources described above. A typical clock distribution net is shown in Figure 9.

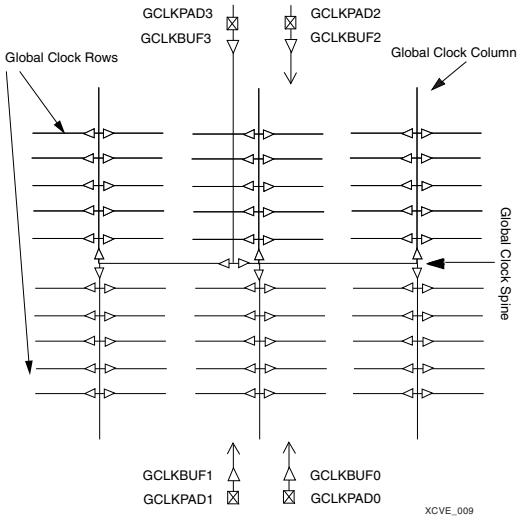

Figure 9: **Global Clock Distribution Network**

Four global buffers are provided, two at the top center of the device and two at the bottom center. These drive the four global nets that in turn drive any clock pin.

Four dedicated clock pads are provided, one adjacent to each of the global buffers. The input to the global buffer is selected either from these pads or from signals in the general purpose routing.

Digital Delay-Locked Loops

There are eight DLLs (Delay-Locked Loops) per device, with four located at the top and four at the bottom, Figure 10. The DLLs can be used to eliminate skew between the clock input pad and the internal clock input pins throughout the device. Each DLL can drive two global clock networks.The DLL monitors the input clock and the distributed clock, and automatically adjusts a clock delay element. Additional delay is introduced such that clock edges arrive at internal flip-flops synchronized with clock edges arriving at the input.

In addition to eliminating clock-distribution delay, the DLL provides advanced control of multiple clock domains. The DLL provides four quadrature phases of the source clock, and can double the clock or divide the clock by 1.5, 2, 2.5, 3, 4, 5, 8, or 16.

Data Registers

The primary data register is the Boundary Scan register. For each IOB pin in the FPGA, bonded or not, it includes three bits for In, Out, and 3-State Control. Non-IOB pins have appropriate partial bit population if input-only or output-only. Each EXTEST CAPTURED-OR state captures all In, Out, and 3-state pins.

The other standard data register is the single flip-flop BYPASS register. It synchronizes data being passed through the FPGA to the next downstream Boundary Scan device.

The FPGA supports up to two additional internal scan chains that can be specified using the BSCAN macro. The macro provides two user pins (SEL1 and SEL2) which are decodes of the USER1 and USER2 instructions respectively. For these instructions, two corresponding pins (T DO1 and TDO2) allow user scan data to be shifted out of TDO.

Likewise, there are individual clock pins (DRCK1 and DRCK2) for each user register. There is a common input pin (TDI) and shared output pins that represent the state of the TAP controller (RESET, SHIFT, and UPDATE).

Bit Sequence

The order within each IOB is: In, Out, 3-State. The input-only pins contribute only the In bit to the Boundary Scan I/O data register, while the output-only pins contributes all three bits.

From a cavity-up view of the chip (as shown in EPIC), starting in the upper right chip corner, the Boundary Scan data-register bits are ordered as shown in Figure 12.

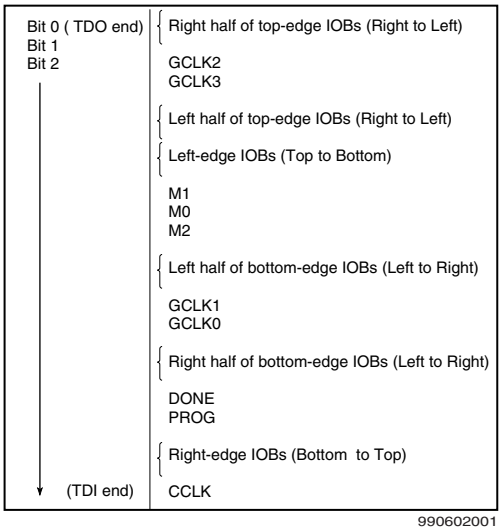

Figure 12: **Boundary Scan Bit Sequence**

BSDL (Boundary Scan Description Language) files for Virtex-E Series devices are available on the Xilinx web site in the File Download area.

Identification Registers

The IDCODE register is supported. By using the IDCODE, the device connected to the JTAG port can be determined.

The IDCODE register has the following binary format:

vvvv:ffff:fffa:aaaa:aaaa:cccc:cccc:ccc1

where

v = the die version number

f = the family code (05 for Virtex-E family)

a = the number of CLB rows (ranges from 16 for

XCV50E to 104 for XCV3200E)

c = the company code (49h for Xilinx)

The USERCODE register is supported. By using the USERCODE, a user-programmable identification code can be loaded and shifted out for examination. The identification code (see Table 7) is embedded in the bitstream during bitstream generation and is valid only after configuration.

Table 7: **IDCODEs Assigned to Virtex-E FPGAs**

FPGA	IDCODE
XCV50E	v0A10093h
XCV100E	v0A14093h
XCV200E	v0A1C093h
XCV300E	v0A20093h
XCV400E	v0A28093h
XCV600E	v0A30093h
XCV1000E	v0A40093h
XCV1600E	v0A48093h
XCV2000E	v0A50093h
XCV2600E	v0A5C093h
XCV3200E	v0A68093h

Note:

Attempting to load an incorrect bitstream causes configuration to fail and can damage the device.

Including Boundary Scan in a Design

Since the Boundary Scan pins are dedicated, no special element needs to be added to the design unless an internal data register (USER1 or USER2) is desired.

If an internal data register is used, insert the Boundary Scan symbol and connect the necessary pins as appropriate.

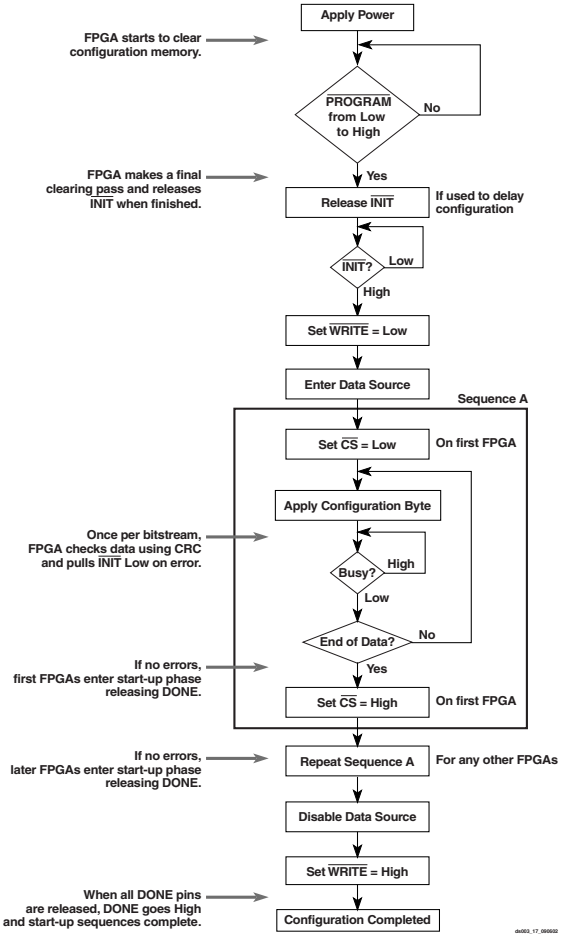

Figure 18: **SelectMAP Flowchart for Write Operations**

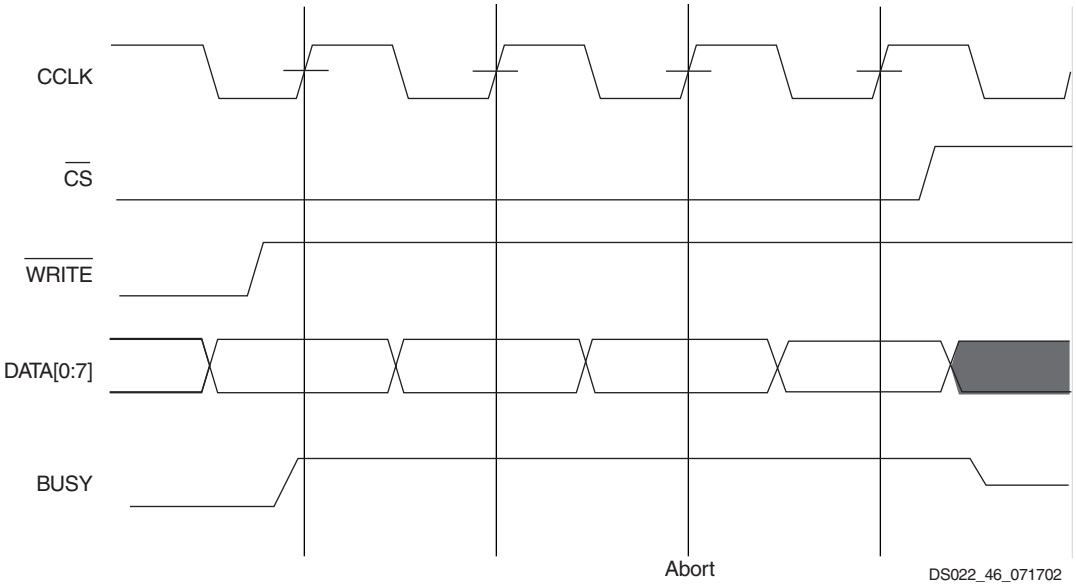

Figure 19: **SelectMAP Write Abort Waveforms**

Boundary Scan Mode

In the Boundary Scan mode, configuration is done through the IEEE 1149.1 Test Access Port. Note that the PROGRAM pin must be pulled High prior to reconfiguration. A Low on the PROGRAM pin resets the TAP controller and no JTAG operations can be performed.

Verilog Initialization Example

```
module MYMEM (CLK, WE, ADDR, DIN, DOUT);
input CLK, WE;
input [8:0] ADDR;
input [7:0] DIN;
output [7:0] DOUT;

wire logic0, logic1;

//synopsys dc_script_begin
//set_attribute ram0 INIT_00
"0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF" -type string
//set_attribute ram0 INIT_01
"FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210" -type string
//synopsys dc_script_end

assign logic0 = 1'b0;
assign logic1 = 1'b1;

RAMB4_S8 ram0 (.WE(WE), .EN(logic1), .RST(logic0), .CLK(CLK), .ADDR(ADDR), .DI(DIN),
.DO(DOUT));
//synopsys translate_off
defparam ram0.INIT_00 =
256h'0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF;
defparam ram0.INIT_01 =
256h'FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210;
//synopsys translate_on
endmodule
```

Using SelectI/O

The Virtex-E FPGA series includes a highly configurable, high-performance I/O resource, called SelectI/O™ to provide support for a wide variety of I/O standards. The SelectI/O resource is a robust set of features including programmable control of output drive strength, slew rate, and input delay and hold time. Taking advantage of the flexibility and SelectI/O features and the design considerations described in this document can improve and simplify system level design.

Introduction

As FPGAs continue to grow in size and capacity, the larger and more complex systems designed for them demand an increased variety of I/O standards. Furthermore, as system clock speeds continue to increase, the need for high performance I/O becomes more important.

While chip-to-chip delays have an increasingly substantial impact on overall system speed, the task of achieving the desired system performance becomes more difficult with the proliferation of low-voltage I/O standards. SelectI/O, the revolutionary input/output resources of Virtex-E devices, resolve this potential problem by providing a highly configurable, high-performance alternative to the I/O resources of more conventional programmable devices. Virtex-E SelectI/O features combine the flexibility and time-to-market advantages of programmable logic with the high performance previously available only with ASICs and custom ICs.

Each SelectI/O block can support up to 20 I/O standards. Supporting such a variety of I/O standards allows the support of a wide variety of applications, from general purpose standard applications to high-speed low-voltage memory buses.

SelectI/O blocks also provide selectable output drive strengths and programmable slew rates for the LVTTL output buffers, as well as an optional, programmable weak pull-up, weak pull-down, or weak “keeper” circuit ideal for use in external bussing applications.

Each Input/Output Block (IOB) includes three registers, one each for the input, output, and 3-state signals within the IOB. These registers are optionally configurable as either a D-type flip-flop or as a level sensitive latch.

The input buffer has an optional delay element used to guarantee a zero hold time requirement for input signals registered within the IOB.

The Virtex-E SelectI/O features also provide dedicated resources for input reference voltage (V_{REF}) and output source voltage (V_{CCO}), along with a convenient banking system that simplifies board design.

By taking advantage of the built-in features and wide variety of I/O standards supported by the SelectI/O features, system-level design and board design can be greatly simplified and improved.

represents a combination of the LVTTL IBUFG and BUFG symbols, such that the output of the BUFGP can connect directly to the clock pins throughout the design.

Unlike previous architectures, the Virtex-E BUFGP symbol can only be placed in a global clock pad location. The LOC property can specify a location for the BUFGP.

OBUF

An OBUF must drive outputs through an external output port. The generic output buffer (OBUF) symbol appears in Figure 40.

The extension to the base name defines which I/O standard the OBUF uses. With no extension specified for the generic OBUF symbol, the assumed standard is slew rate limited LVTTL with 12 mA drive strength.

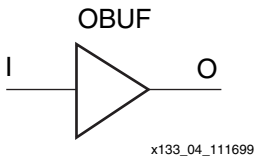

Figure 40: **Virtex-E Output Buffer (OBUF) Symbol**

The LVTTL OBUF additionally can support one of two slew rate modes to minimize bus transients. By default, the slew rate for each output buffer is reduced to minimize power bus transients when switching non-critical signals.

LVTTL output buffers have selectable drive strengths.

The format for LVTTL OBUF symbol names is as follows:

OBUF_<slew_rate>_<drive_strength>

where <slew_rate> is either F (Fast) or S (Slow), and <drive_strength> is specified in milliamps (2, 4, 6, 8, 12, 16, or 24).

The following list details variations of the OBUF symbol.

- OBUF
- OBUF_S_2
- OBUF_S_4
- OBUF_S_6
- OBUF_S_8
- OBUF_S_12
- OBUF_S_16
- OBUF_S_24
- OBUF_F_2
- OBUF_F_4
- OBUF_F_6
- OBUF_F_8
- OBUF_F_12
- OBUF_F_16
- OBUF_F_24
- OBUF_LVCMOS2
- OBUF_PCI33_3
- OBUF_PCI66_3
- OBUF_GTL
- OBUF_GTLP
- OBUF_HSTL_I
- OBUF_HSTL_III
- OBUF_HSTL_IV
- OBUF_SSTL3_I
- OBUF_SSTL3_II
- OBUF_SSTL2_I
- OBUF_SSTL2_II
- OBUF_CTT
- OBUF_AGP
- OBUF_LVCMOS18
- OBUF_LVDS
- OBUF_LVPECL

The Virtex-E series supports eight banks for the HQ and PQ packages. The CS packages support four V_{CCO} banks.

OBUF placement restrictions require that within a given V_{CCO} bank each OBUF share the same output source drive voltage. Input buffers of any type and output buffers that do not require V_{CCO} can be placed within any V_{CCO} bank. Table 20 summarizes the Virtex-E output compatibility requirements. The LOC property can specify a location for the OBUF.

Table 20: **Output Standards Compatibility Requirements**

Rule 1	Only outputs with standards that share compatible V_{CCO} can be used within the same bank.
Rule 2	There are no placement restrictions for outputs with standards that do not require a V_{CCO}.
V_{CCO}	Compatible Standards
3.3	LVTTL, SSTL3_I, SSTL3_II, CTT, AGP, GTL, GTL+, PCI33_3, PCI66_3
2.5	SSTL2_I, SSTL2_II, LVCMOS2, GTL, GTL+
1.5	HSTL_I, HSTL_III, HSTL_IV, GTL, GTL+

OBUFT

The generic 3-state output buffer OBUFT (see Figure 41) typically implements 3-state outputs or bidirectional I/O.

The extension to the base name defines which I/O standard OBUFT uses. With no extension specified for the generic OBUFT symbol, the assumed standard is slew rate limited LVTTL with 12 mA drive strength.

The LVTTL OBUFT additionally can support one of two slew rate modes to minimize bus transients. By default, the slew rate for each output buffer is reduced to minimize power bus transients when switching non-critical signals.

Power-On Power Supply Requirements

Xilinx FPGAs require a certain amount of supply current during power-on to insure proper device operation. The actual current consumed depends on the power-on ramp rate of the power supply. This is the time required to reach the nominal power supply voltage of the device[1] from 0V. The fastest ramp rate is 0V to nominal voltage in 2 ms, and the slowest allowed ramp rate is 0V to nominal voltage in 50 ms. For more details on power supply requirements, see XAPP158 on www.xilinx.com.

Product (Commercial Grade)	Description(2)	Current Requirement(3)
XCV50E - XCV600E	Minimum required current supply	500 mA
XCV812E - XCV2000E	Minimum required current supply	1 A
XCV2600E - XCV3200E	Minimum required current supply	1.2 A
Virtex-E Family, Industrial Grade	Minimum required current supply	2 A

Notes:
1. Ramp rate used for this specification is from 0 - 1.8 V DC. Peak current occurs on or near the internal power-on reset threshold and lasts for less than 3 ms.
2. Devices are guaranteed to initialize properly with the minimum current available from the power supply as noted above.
3. Larger currents might result if ramp rates are forced to be faster.

DC Input and Output Levels

Values for V_{IL} and V_{IH} are recommended input voltages. Values for I_{OL} and I_{OH} are guaranteed over the recommended operating conditions at the V_{OL} and V_{OH} test points. Only selected standards are tested. These are chosen to ensure that all standards meet their specifications. The selected standards are tested at minimum V_{CCO} with the respective V_{OL} and V_{OH} voltage levels shown. Other standards are sample tested.

Input/Output Standard	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}
	V, Min	V, Max	V, Min	V, Max	V, Max	V, Min	mA	mA
LVTTL(1)	– 0.5	0.8	2.0	3.6	0.4	2.4	24	– 24
LVCMOS2	– 0.5	0.7	1.7	2.7	0.4	1.9	12	– 12
LVCMOS18	– 0.5	35% V_{CCO}	65% V_{CCO}	1.95	0.4	V_{CCO} – 0.4	8	– 8
PCI, 3.3 V	– 0.5	30% V_{CCO}	50% V_{CCO}	V_{CCO} + 0.5	10% V_{CCO}	90% V_{CCO}	Note 2	Note 2
GTL	– 0.5	V_{REF} – 0.05	V_{REF} + 0.05	3.6	0.4	n/a	40	n/a
GTL+	– 0.5	V_{REF} – 0.1	V_{REF} + 0.1	3.6	0.6	n/a	36	n/a
HSTL I(3)	– 0.5	V_{REF} – 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCO} – 0.4	8	–8
HSTL III	– 0.5	V_{REF} – 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCO} – 0.4	24	–8
HSTL IV	– 0.5	V_{REF} – 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCO} – 0.4	48	–8
SSTL3 I	– 0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	V_{REF} – 0.6	V_{REF} + 0.6	8	–8
SSTL3 II	– 0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	V_{REF} – 0.8	V_{REF} + 0.8	16	–16
SSTL2 I	– 0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	V_{REF} – 0.61	V_{REF} + 0.61	7.6	–7.6
SSTL2 II	– 0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	V_{REF} – 0.80	V_{REF} + 0.80	15.2	–15.2

Virtex-E Pin-to-Pin Input Parameter Guidelines

All devices are 100% functionally tested. Listed below are representative values for typical pin locations and normal clock loading. Values are expressed in nanoseconds unless otherwise noted

Global Clock Set-Up and Hold for LVTTL Standard, *with* DLL

Description[1]	Symbol	Device	Speed Grade[2, 3]				Units
			Min	-8	-7	-6	
Input Setup and Hold Time Relative to Global Clock Input Signal for LVTTL Standard. For data input with different standards, adjust the setup time delay by the values shown in **IOB Input Switching Characteristics Standard Adjustments**, page 8.							
No Delay	T_{PSDLL}/T_{PHDLL}	XCV50E	1.5 / –0.4	1.5 / –0.4	1.6 / –0.4	1.7 / –0.4	ns
Global Clock and IFF, with DLL		XCV100E	1.5 / –0.4	1.5 / –0.4	1.6 / –0.4	1.7 / –0.4	ns
		XCV200E	1.5 / –0.4	1.5 / –0.4	1.6 / –0.4	1.7 / –0.4	ns
		XCV300E	1.5 / –0.4	1.5 / –0.4	1.6 / –0.4	1.7 / –0.4	ns
		XCV400E	1.5 / –0.4	1.5 / –0.4	1.6 / –0.4	1.7 / –0.4	ns
		XCV600E	1.5 / –0.4	1.5 / –0.4	1.6 / –0.4	1.7 / –0.4	ns
		XCV1000E	1.5 / –0.4	1.5 / –0.4	1.6 / –0.4	1.7 / –0.4	ns
		XCV1600E	1.5 / –0.4	1.5 / –0.4	1.6 / –0.4	1.7 / –0.4	ns
		XCV2000E	1.5 / –0.4	1.5 / –0.4	1.6 / –0.4	1.7 / –0.4	ns
		XCV2600E	1.5 / –0.4	1.5 / –0.4	1.6 / –0.4	1.7 / –0.4	ns
		XCV3200E	1.5 / –0.4	1.5 / –0.4	1.6 / –0.4	1.7 / –0.4	ns

Notes:
1. IFF = Input Flip-Flop or Latch
2. Setup time is measured relative to the Global Clock input signal with the fastest route and the lightest load. Hold time is measured relative to the Global Clock input signal with the slowest route and heaviest load.
3. DLL output jitter is already included in the timing calculation.

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
12/7/99	1.0	Initial Xilinx release.
1/10/00	1.1	Re-released with spd.txt v. 1.18, FG860/900/1156 package information, and additional DLL, Select RAM and SelectI/O information.
1/28/00	1.2	Added Delay Measurement Methodology table, updated SelectI/O section, Figures 30, 54, & 55, text explaining Table 5, T_{BYP} values, buffered Hex Line info, p. 8, I/O Timing Measurement notes, notes for Tables 15, 16, and corrected F1156 pinout table footnote references.
2/29/00	1.3	Updated pinout tables, V_{CC} page 20, and corrected Figure 20.
5/23/00	1.4	Correction to table on p. 22.
7/10/00	1.5	• Numerous minor edits. • Data sheet upgraded to Preliminary. • Preview -8 numbers added to **Virtex-E Electrical Characteristics** tables.
8/1/00	1.6	• Reformatted entire document to follow new style guidelines. • Changed speed grade values in tables on pages 35-37.
9/20/00	1.7	• Min values added to **Virtex-E Electrical Characteristics** tables. • XCV2600E and XCV3200E numbers added to **Virtex-E Electrical Characteristics** tables (Module 3). • Corrected user I/O count for XCV100E device in Table 1 (Module 1). • Changed several pins to “No Connect in the XCV100E“ and removed duplicate V_{CCINT} pins in Table ~ (Module 4). • Changed pin J10 to “No connect in XCV600E” in Table 74 (Module 4). • Changed pin J30 to “VREF option only in the XCV600E” in Table 74 (Module 4). • Corrected pair 18 in Table 75 (Module 4) to be “AO in the XCV1000E, XCV1600E“.
11/20/00	1.8	• Upgraded speed grade -8 numbers in **Virtex-E Electrical Characteristics** tables to Preliminary. • Updated minimums in Table 13 and added notes to Table 14. • Added to note 2 to **Absolute Maximum Ratings**. • Changed speed grade -8 numbers for $T_{SHCKO32}$, T_{REG}, T_{BCCS}, and T_{ICKOF} • Changed all minimum hold times to –0.4 under **Global Clock Set-Up and Hold for LVTTL Standard, with DLL**. • Revised maximum T_{DLLPW} in -6 speed grade for **DLL Timing Parameters**. • Changed GCLK0 to BA22 for FG860 package in Table 46.
2/12/01	1.9	• Revised footnote for Table 14. • Added numbers to **Virtex-E Electrical Characteristics** tables for XCV1000E and XCV2000E devices. • Updated Table 27 and Table 78 to include values for XCV400E and XCV600E devices. • Revised Table 62 to include pinout information for the XCV400E and XCV600E devices in the BG560 package. • Updated footnotes 1 and 2 for Table 76 to include XCV2600E and XCV3200E devices.
4/02/01	2.0	• Updated numerous values in **Virtex-E Switching Characteristics** tables. • Converted data sheet to modularized format. See the **Virtex-E Data Sheet** section.
4/19/01	2.1	• Updated values in **Virtex-E Switching Characteristics** tables.

PQ240 Differential Pin Pairs

Virtex-E devices have differential pin pairs that can also provide other functions when not used as a differential pair. A √ in the AO column indicates that the pin pair can be used as an asynchronous output for all devices provided in this package. Pairs with a note number in the AO column are device dependent. They can have asynchronous outputs if the pin pair are in the same CLB row and column in the device. Numbers in this column refer to footnotes that indicate which devices have pin pairs than can be asynchronous outputs. The Other Functions column indicates alternative function(s) not available when the pair is used as a differential pair or differential clock.

Table 7: **PQ240 Differential Pin Pair Summary XCV50E, XCV100E, XCV200E, XCV300E, XCV400E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
Global Differential Clock					
0	4	P92	P93	NA	IO_DLL_L40P
1	5	P89	P87	NA	IO_DLL_L40N
2	1	P210	P209	NA	IO_DLL_L6P
3	0	P213	P215	NA	IO_DLL_L6N
IO LVDS Total Pairs: 64, Asynchronous Outputs Pairs: 27					
0	0	P236	P237	1	VREF
1	0	P234	P235	√	-
2	0	P228	P229	√	VREF
3	0	P223	P224	√	-
4	0	P220	P221	3	-
5	0	P217	P218	3	VREF
6	1	P209	P215	NA	IO_LVDS_DLL
7	1	P205	P206	3	VREF
8	1	P202	P203	3	-
9	1	P199	P200	√	-
10	1	P194	P195	√	VREF
11	1	P191	P192	√	VREF
12	1	P188	P189	√	-
13	1	P186	P187	1	VREF
14	1	P184	P185	√	CS
15	2	P178	P177	√	DIN, D0
16	2	P174	P173	2	-
17	2	P171	P170	3	VREF
18	2	P168	P167	4	D1, VREF
19	2	P163	P162	√	D2
20	2	P160	P159	2	-
21	2	P157	P156	4	D3, VREF
22	2	P155	P154	5	VREF
23	2	P153	P152	√	-
24	3	P145	P144	4	D4, VREF
25	3	P142	P141	2	-
26	3	P139	P138	√	D5
27	3	P134	P133	4	VREF
28	3	P131	P130	3	VREF
29	3	P128	P127	2	-
30	3	P126	P125	6	VREF
31	3	P124	P123	√	INIT
32	4	P118	P117	√	-
33	4	P114	P113	√	-
34	4	P111	P110	√	VREF
35	4	P108	P107	√	VREF
36	4	P103	P102	√	-
37	4	P100	P99	3	-
38	4	P97	P96	3	VREF
39	4	P95	P94	7	VREF
40	5	P93	P87	NA	IO_LVDS_DLL
41	5	P84	P82	8	VREF
42	5	P79	P78	√	-
43	5	P74	P73	√	VREF
44	5	P71	P70	√	VREF
45	5	P68	P67	√	-
46	5	P66	P65	1	VREF
47	5	P64	P63	√	-

Table 8: **HQ240 — XCV600E, XCV1000E**

Pin #	Pin Description	Bank
P138	IO_D5_L26N_YY	3
P137	VCCINT	NA
P136	VCCO	3
P135	GND	NA
P134	IO_D6_L27P_Y	3
P133	IO_VREF_L27N_Y	3
P132	IO_VREF	3
P131	IO_L28P_Y	3
P130	IO_VREF_L28N_Y	3
P129	GND	NA
P128	IO_L29P_Y	3
P127	IO_L29N_Y	3
P126	IO_VREF_L30P_Y	3
P125	IO_L30N_Y	3
P124	IO_D7_L31P_YY	3
P123	IO_INIT_L31N_YY	3
P122	PROGRAM	NA
P121	VCCO	3
P120	DONE	3
P119	GND	NA
P118	IO_L32P_YY	4
P117	IO_L32N_YY	4
P116	VCCO	4
P115	IO_VREF	4
P114	IO_L33P_YY	4
P113	IO_L33N_YY	4
P112	GND	NA
P111	IO_VREF_L34P_YY	4
P110	IO_L34N_YY	4
P109	IO_VREF	4
P108	IO_VREF_L35P_YY	4
P107	IO_L35N_YY	4
P106	GND	NA
P105	VCCO	4
P104	VCCINT	NA
P103	IO_L36P_YY	4

Table 8: **HQ240 — XCV600E, XCV1000E**

Pin #	Pin Description	Bank
P102	IO_L36N_YY	4
P101[1]	IO_VREF	4
P100	IO_L37P_Y	4
P99	IO_L37N_Y	4
P98	GND	NA
P97	IO_VREF_L38P_Y	4
P96	IO_L38N_Y	4
P95	IO_L39P	4
P94	IO_VREF_L39N	4
P93	IO_LVDS_DLL_L40P	4
P92	GCK0	4
P91	GND	NA
P90	VCCO	4
P89	GCK1	5
P88	VCCINT	NA
P87	IO_LVDS_DLL_L40N	5
P86	IO_VREF	5
P85	VCCO	5
P84	IO_VREF_L41P	5
P83	GND	NA
P82	IO_L41N	5
P81	IO	5
P80[1]	IO_VREF	5
P79	IO_L42P_YY	5
P78	IO_L42N_YY	5
P77	VCCINT	NA
P76	VCCO	5
P75	GND	NA
P74	IO_L43P_YY	5
P73	IO_VREF_L43N_YY	5
P72	IO_VREF	5
P71	IO_L44P_YY	5
P70	IO_VREF_L44N_YY	5
P69	GND	NA
P68	IO_L45P_YY	5
P67	IO_L45N_YY	5

Table 10: **BG352 — XCV100E, XCV200E, XCV300E**

Bank	Pin Description	Pin #
2	IO_D3_L30N _Y	M3
2	IO_L31P	M2
2	IO_L31N	M1
2	IO	N3[1]
2	IO_L32P_YY	N4
2	IO_L32N_YY	N2
3	IO	P1
3	IO	P3[1]
3	IO_L33P	R1
3	IO_L33N	R2
3	IO_D4_L34P _Y	R3
3	IO_VREF_3_L34N _Y	R4
3	IO_L35P_YY	T2
3	IO_L35N_YY	U2
3	IO	T3[1]
3	IO_L36P	T4
3	IO_L36N	V1
3	IO	V2[1]
3	IO_L37P_YY	U3
3	IO_D5_L37N_YY	U4
3	IO_D6_L38P _Y	V3
3	IO_VREF_3_L38N _Y	V4
3	IO_L39P _Y	Y1
3	IO_L39N _Y	Y2
3	IO	W3
3	IO	W4[1]
3	IO	AA1[1]
3	IO_L40P_Y	AA2
3	IO_VREF_3_L40N_Y	Y3
3	IO_L41P_YY	AC1
3	IO_L41N_YY	AB2
3	IO	AA3[1]
3	IO_L42P_YY	AA4

Table 10: **BG352 — XCV100E, XCV200E, XCV300E**

Bank	Pin Description	Pin #
3	IO_VREF_3_L42N_YY	AC2[2]
3	IO	AB3
3	IO	AD1[1]
3	IO	AB4[1]
3	IO_D7_L43P_YY	AC3
3	IO_INIT_L43N_YY	AD2
4	IO_L44P_YY	AC5
4	IO_L44N_YY	AD4
4	IO	AE3[1]
4	IO	AD5[1]
4	IO	AC6
4	IO_VREF_4_L45P_YY	AE4[2]
4	IO_L45N_YY	AF3
4	IO	AF4[1]
4	IO_L46P_YY	AC7
4	IO_L46N_YY	AD6
4	IO_VREF_4_L47P_YY	AE5
4	IO_L47N_YY	AE6
4	IO	AD7[1]
4	IO	AE7[1]
4	IO_L48P	AF6
4	IO_L48N	AC9
4	IO	AD8
4	IO_VREF_4_L49P_YY	AE8
4	IO_L49N_YY	AF7
4	IO_L50P_YY	AD9
4	IO_L50N_YY	AE9
4	IO	AD10[1]
4	IO_L51P	AF9
4	IO_L51N	AC11
4	IO	AE10[1]
4	IO_L52P_Y	AD11
4	IO_L52N_Y	AE11

Table 16: **FG256 Package — XCV50E, XCV100E, XCV200E, XCV300E**

Bank	Pin Description	Pin #
7	IO_L74N_Y	G4
7	IO_VREF_L74P_Y	H3
7	IO_L75N_YY	G2
7	IO_L75P_YY	F5
7	IO_L76N	F4
7	IO_L76P	F1
7	IO_L77N_YY	G3
7	IO_L77P_YY	F2
7	IO_L78N_Y	E1
7	IO_VREF_L78P_Y	D1[1]
7	IO_L79N	E4
7	IO_L79P	E2
7	IO_L80N_Y	F3
7	IO_VREF_L80P_Y	C1
7	IO_L81N_YY	D2
7	IO_L81P_YY	E3
7	IO_VREF_L82N	B1[2]
7	IO_L82P	A2
2	CCLK	D15
3	DONE	R14
NA	DXN	R4
NA	DXP	P4
NA	M0	N3
NA	M1	P2
NA	M2	R3
NA	PROGRAM	P15
NA	TCK	C4
NA	TDI	A15
2	TDO	B14
NA	TMS	D3
NA	VCCINT	C3
NA	VCCINT	C14
NA	VCCINT	D4

Table 16: **FG256 Package — XCV50E, XCV100E, XCV200E, XCV300E**

Bank	Pin Description	Pin #
NA	VCCINT	D13
NA	VCCINT	E5
NA	VCCINT	E12
NA	VCCINT	M5
NA	VCCINT	M12
NA	VCCINT	N4
NA	VCCINT	N13
NA	VCCINT	P3
NA	VCCINT	P14
0	VCCO	F8
0	VCCO	E8
1	VCCO	F9
1	VCCO	E9
2	VCCO	H12
2	VCCO	H11
3	VCCO	J12
3	VCCO	J11
4	VCCO	M9
4	VCCO	L9
5	VCCO	M8
5	VCCO	L8
6	VCCO	J6
6	VCCO	J5
7	VCCO	H6
7	VCCO	H5
NA	GND	T16
NA	GND	T1
NA	GND	R15
NA	GND	R2
NA	GND	L11
NA	GND	L10
NA	GND	L7
NA	GND	L6

Table 17: **FG256 Differential Pin Pair Summary XCV50E, XCV100E, XCV200E, XCV300E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
19	2	C15	D14	√	DIN, D0
20	2	B16	E13	6	VREF
21	2	C16	E14	√	-
22	2	F13	E15	1	VREF
23	2	F12	D16	5	-
24	2	F14	E16	3	D1
25	2	F15	G13	√	D2
26	2	F16	G12	6	-
27	2	G15	G14	√	-
28	2	H13	G16	3	D3
29	2	J13	H15	4	-
30	2	H14	H16	√	-
31	3	K15	J14	4	-
32	3	J16	K16	3	VREF
33	3	K12	L15	√	-
34	3	K13	L16	6	-
35	3	K14	M16	√	D5
36	3	N16	L13	3	VREF
37	3	P16	L12	5	-
38	3	M15	L14	1	VREF
39	3	M14	R16	√	-
40	3	M13	T15	6	VREF
41	3	N14	N15	√	INIT
42	4	T14	P13	√	-
43	4	P12	R13	7	VREF
44	4	N12	T13	√	-
45	4	T12	P11	√	VREF
46	4	R12	N11	2	-
47	4	T11	M11	√	VREF
48	4	R11	T10	√	-
49	4	R10	M10	1	-
50	4	P9	T9	1	VREF
51	4	N10	R9	1	-
52	5	N9	T8	NA	IO_LVDS_DLL
53	5	R7	P8	1	VREF
54	5	P7	T6	1	-

Table 17: **FG256 Differential Pin Pair Summary XCV50E, XCV100E, XCV200E, XCV300E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
55	5	M7	R6	√	-
56	5	P6	R5	√	VREF
57	5	N6	T5	2	-
58	5	M6	T4	√	VREF
59	5	T3	P5	√	-
60	5	T2	N5	7	VREF
61	6	R1	M3	√	-
62	6	N2	M4	6	VREF
63	6	P1	L5	√	-
64	6	L3	N1	1	VREF
65	6	L4	M2	5	-
66	6	K4	M1	3	VREF
67	6	L1	L2	√	-
68	6	K1	K3	6	-
69	6	K5	K2	√	-
70	6	J1	J3	3	VREF
71	6	H1	J4	4	-
72	7	H4	G1	√	-
73	7	H2	G5	4	-
74	7	H3	G4	3	VREF
75	7	F5	G2	√	-
76	7	F1	F4	6	-
77	7	F2	G3	√	-
78	7	D1	E1	3	VREF
79	7	E2	E4	5	-
80	7	C1	F3	1	VREF
81	7	E3	D2	√	-
82	7	A2	B1	6	VREF

Notes:
1. AO in the XCV50E, 200E, 300E.
2. AO in the XCV50E, 200E.
3. AO in the XCV50E, 300E.
4. AO in the XCV100E, 200E.
5. AO in the XCV200E.
6. AO in the XCV100E.
7. AO in the XCV50E.

Table 20: **FG676 — XCV400E, XCV600E**

Bank	Pin Description	Pin #
7	IO	D2
7	IO	D3
7	IO	E1
7	IO	G1
7	IO	H2
7	IO	J1[1]
7	IO	L1[1]
7	IO	M1[1]
7	IO	N1[1]
7	IO_L160N_YY	N5
7	IO_L160P_YY	N8
7	IO_L161N_YY	N6
7	IO_L161P_YY	N3
7	IO_L162N_Y	N4
7	IO_VREF_L162P_Y	M2
7	IO_L163N_Y	N7
7	IO_L163P_Y	M7
7	IO_L164N_YY	M6
7	IO_L164P_YY	M3
7	IO_L165N_YY	M4
7	IO_VREF_L165P_YY	M5
7	IO_L166N_Y	L3
7	IO_L166P_Y	L7
7	IO_L167N_Y	L6
7	IO_L167P_Y	K2
7	IO_L168N_Y	L4
7	IO_L168P_Y	K1
7	IO_L169N_Y	K3
7	IO_L169P_Y	L5
7	IO_L170N_YY	K5
7	IO_L170P_YY	J3
7	IO_L171N_YY	K4
7	IO_L171P_YY	J4
7	IO_L172N_YY	H3
7	IO_VREF_L172P_YY	K6
7	IO_L173N_YY	K7
7	IO_L173P_YY	G3
7	IO_L174N_Y	J5
7	IO_VREF_L174P_Y	H1[2]
7	IO_L175N_Y	G2
7	IO_L175P_Y	J6
7	IO_L176N_YY	J7
7	IO_L176P_YY	F1
7	IO_L177N_YY	H4
7	IO_VREF_L177P_YY	G4
7	IO_L178N_Y	F3
7	IO_L178P_Y	H5
7	IO_L179N_Y	E2
7	IO_L179P_Y	H6
7	IO_L180N_Y	G5
7	IO_VREF_L180P_Y	F4
7	IO_L181N_Y	H7
7	IO_L181P_Y	G6
7	IO_L182N_YY	E3
7	IO_L182P_YY	E4
2	CCLK	D24
3	DONE	AB21
NA	DXN	AB7
NA	DXP	Y8
NA	M0	AD4
NA	M1	W7
NA	M2	AB6
NA	PROGRAM	AA22
NA	TCK	E6
NA	TDI	D22
2	TDO	C23
NA	TMS	F5
NA	NC	T25
NA	NC	T2
NA	NC	P2
NA	NC	N25
NA	NC	L25

Table 21: **FG676 Differential Pin Pair Summary**
XCV400E, XCV600E

Pair	Bank	P Pin	N Pin	AO	Other Functions
120	5	AD11	Y12	√	-
121	5	AB11	AD10	NA	-
122	5	AC11	AE10	√	-
123	5	AC10	AA11	√	-
124	5	Y11	AD9	1	-
125	5	AB10	AF9	√	-
126	5	AD8	AA10	√	VREF
127	5	AE8	Y10	√	-
128	5	AC9	AF8	1	VREF
129	5	AF7	AB9	1	-
130	5	AA9	AF6	√	-
131	5	AC8	AC7	√	VREF
132	5	AD6	Y9	√	-
133	5	AE5	AA8	√	-
134	5	AC6	AB8	√	VREF
135	5	AD5	AA7	√	-
136	5	AF4	AC5	2	-
137	6	AC3	AA5	√	-
138	6	AB4	AC2	√	-
139	6	AA4	W6	2	-
140	6	Y5	AB3	1	VREF
141	6	V7	AB2	1	-
142	6	Y4	AB1	√	-
143	6	W5	V5	√	VREF
144	6	V6	AA1	√	-
145	6	Y3	W4	2	-
146	6	U7	Y1	1	VREF
147	6	V4	W1	√	-
148	6	U6	W2	√	VREF
149	6	T5	V3	√	-
150	6	U4	U5	√	-
151	6	U3	T7	2	-
152	6	T6	U2	1	-
153	6	T4	U1	1	-

Table 21: **FG676 Differential Pin Pair Summary**
XCV400E, XCV600E

Pair	Bank	P Pin	N Pin	AO	Other Functions
154	6	T3	R7	1	-
155	6	R6	R4	√	VREF
156	6	R5	R3	√	-
157	6	P7	P8	2	-
158	6	P6	R1	1	VREF
159	6	P4	P5	√	-
160	7	N8	N5	√	-
161	7	N3	N6	√	-
162	7	M2	N4	1	VREF
163	7	M7	N7	2	-
164	7	M3	M6	√	-
165	7	M5	M4	√	VREF
166	7	L7	L3	1	-
167	7	K2	L6	1	-
168	7	K1	L4	1	-
169	7	L5	K3	2	-
170	7	J3	K5	√	-
171	7	J4	K4	√	-
172	7	K6	H3	√	VREF
173	7	G3	K7	√	-
174	7	H1	J5	1	VREF
175	7	J6	G2	2	-
176	7	F1	J7	√	-
177	7	G4	H4	√	VREF
178	7	H5	F3	1	-
179	7	H6	E2	2	-
180	7	F4	G5	1	VREF
181	7	G6	H7	2	-
182	7	E4	E3	√	-

Notes:
1. AO in the XCV600E.
2. AO in the XCV400E.

Table 22: **FG680 - XCV600E, XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
5	IO_L166P_YY	AV26
5	IO_L166N_YY	AW27
5	IO_L167P_Y	AU26
5	IO_L167N_Y	AV27
5	IO_L168P_Y	AT26
5	IO_L168N_Y	AW28
5	IO_L169P_YY	AU27
5	IO_L169N_YY	AV28
5	IO_L170P_YY	AW29
5	IO_VREF_L170N_YY	AT27
5	IO_L171P_Y	AW30
5	IO_L171N_Y	AU28
5	IO_L172P_Y	AV30
5	IO_L172N_Y	AV29
5	IO_L173P_YY	AW31
5	IO_VREF_L173N_YY	AU29
5	IO_L174P_YY	AV31
5	IO_L174N_YY	AT29
5	IO_L175P_Y	AW32
5	IO_VREF_L175N_Y	AU30[3]
5	IO_L176P_Y	AW33
5	IO_L176N_Y	AT30
5	IO_L177P_YY	AV33
5	IO_VREF_L177N_YY	AU31
5	IO_L178P_YY	AT31
5	IO_L178N_YY	AW34
5	IO_L179P_Y	AV32
5	IO_L179N_Y	AV34
5	IO_L180P_Y	AU32
5	IO_L180N_Y	AW35
5	IO_L181P_YY	AT32
5	IO_VREF_L181N_YY	AV35
5	IO_L182P_YY	AU33
5	IO_L182N_YY	AW36
5	IO_L183P_Y	AT33
5	IO_VREF_L183N_Y	AV36[1]

Table 22: **FG680 - XCV600E, XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
5	IO_L184P_Y	AU34
5	IO_L184N_Y	AU36
6	IO	W39
6	IO	AR37
6	IO	AR39
6	IO_L185N_YY	AR36
6	IO_L185P_YY	AT38
6	IO_L186N_Y	AR38
6	IO_L186P_Y	AP36
6	IO_VREF_L187N	AT39[1]
6	IO_L187P	AP37
6	IO_L188N	AP38
6	IO_L188P	AP39
6	IO_VREF_L189N_Y	AN36
6	IO_L189P_Y	AN38
6	IO_L190N_YY	AN37
6	IO_L190P_YY	AN39
6	IO_L191N	AM36
6	IO_L191P	AM38
6	IO_L192N_Y	AM37
6	IO_L192P_Y	AL36
6	IO_VREF_L193N_YY	AM39
6	IO_L193P_YY	AL37
6	IO_L194N_YY	AL38
6	IO_L194P_YY	AK36
6	IO_VREF_L195N	AL39[3]
6	IO_L195P	AK37
6	IO_L196N	AK38
6	IO_L196P	AJ36
6	IO_VREF_L197N_YY	AK39
6	IO_L197P_YY	AJ37
6	IO_L198N_YY	AJ38
6	IO_L198P_YY	AH37
6	IO_L199N	AJ39
6	IO_L199P	AH38

Table 27: **FG900 Differential Pin Pair Summary XCV600E, XCV1000E, XCV1600E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
256	7	N6	M6	1	-
257	7	N1	N5	4	-
258	7	M5	M4	√	-
259	7	M1	M2	1	VREF
260	7	L2	L4	4	-
261	7	L5	M7	3	-
262	7	M8	L1	4	-
263	7	M9	K2	1	-
264	7	M10	L3	NA	-
265	7	K1	K5	√	-
266	7	K3	L6	√	VREF
267	7	K4	L7	4	-
268	7	J5	L8	4	-
269	7	H4	K6	4	VREF
270	7	K7	H1	4	-
271	7	J2	J7	2	-
272	7	G2	H5	√	-
273	7	G5	L9	√	VREF
274	7	K8	F3	1	-
275	7	E1	G3	4	-
276	7	E2	H6	√	-
277	7	K9	E4	1	VREF
278	7	F4	J8	4	-
279	7	H7	D1	3	-
280	7	C2	G6	4	VREF
281	7	F5	D2	1	-
282	7	K10	D3	4	-

Notes:
1. AO in the XCV600E, 1000E.
2. AO in the XCV1000E.
3. AO in the XCV1600E.
4. AO in the XCV1000E, XCV1600E.

FG1156 Fine-Pitch Ball Grid Array Package

XCV1000E, XCV1600E, XCV2000E, XCV2600E, and XCV3200E devices in the FG1156 fine-pitch Ball Grid Array package have footprint compatibility. Pins labeled IO_VREF can be used as either V_{REF} or general I/O, unless indicated in the footnotes. If the pin is not used as V_{REF}, it can be used as general I/O. Immediately following Table 28, see Table 29 for Differential Pair information.

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
0	GCK3	E17
0	IO	B4
0	IO	B9
0	IO	B10
0	IO	D9[3]
0	IO	D16
0	IO	E7[3]
0	IO	E11[3]
0	IO	E13[3]
0	IO	E16[3]
0	IO	F17[3]
0	IO	J12[3]
0	IO	J13[3]
0	IO	J14[3]
0	IO	K11[3]
0	IO_L0N_Y	F7
0	IO_L0P_Y	H9
0	IO_L1N_Y	C5
0	IO_L1P_Y	J10
0	IO_VREF_L2N_Y	E6
0	IO_L2P_Y	D6
0	IO_L3N_Y	A4
0	IO_L3P_Y	G8
0	IO_L4N_YY	C6
0	IO_L4P_YY	J11
0	IO_VREF_L5N_YY	G9
0	IO_L5P_YY	F8
0	IO_L6N_YY	A5[4]

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
2	IO_L92N_Y	H29
2	IO_L93P_YY	J28[4]
2	IO_L93N_YY	E33[5]
2	IO_L94P_YY	H28
2	IO_L94N_YY	H30
2	IO_L95P_Y	H32
2	IO_L95N_Y	K28
2	IO_L96P_Y	L27[4]
2	IO_L96N_Y	F33[5]
2	IO_L97P_Y	M26
2	IO_L97N_Y	E34
2	IO_VREF_L98P_YY	H31
2	IO_L98N_YY	G32
2	IO_L99P_YY	N25[4]
2	IO_L99N_YY	J31[5]
2	IO_L100P_YY	J30
2	IO_L100N_YY	G33
2	IO_VREF_L101P_Y	H34[2]
2	IO_L101N_Y	J29
2	IO_L102P	M27[4]
2	IO_L102N	H33[5]
2	IO_L103P_Y	K29
2	IO_L103N_Y	J34
2	IO_VREF_L104P_YY	L29
2	IO_L104N_YY	J33
2	IO_L105P_YY	M28
2	IO_L105N_YY	K34
2	IO_L106P_Y	N27
2	IO_L106N_Y	L34
2	IO_VREF_L107P_YY	K33
2	IO_D1_L107N_YY	P26
2	IO_L108P_Y	R25
2	IO_L108N_Y	M34
2	IO_L109P_Y	L31

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
2	IO_L109N_Y	L33
2	IO_L110P_Y	P27
2	IO_L110N_Y	M33
2	IO_L111P	M31
2	IO_L111N	R26
2	IO_L112P_Y	N30
2	IO_L112N_Y	P28
2	IO_VREF_L113P_Y	N29
2	IO_L113N_Y	N33
2	IO_L114P_YY	T25[4]
2	IO_L114N_YY	N34[5]
2	IO_L115P_YY	P34
2	IO_L115N_YY	R27
2	IO_L116P_Y	P29
2	IO_L116N_Y	P31
2	IO_L117P_Y	P33[4]
2	IO_L117N_Y	T26[5]
2	IO_L118P_Y	R34
2	IO_L118N_Y	R28
2	IO_VREF_L119P_YY	N31
2	IO_D3_L119N_YY	N32
2	IO_L120P_YY	P30[4]
2	IO_L120N_YY	R33[5]
2	IO_L121P_YY	R29
2	IO_L121N_YY	T34
2	IO_L122P_Y	R30
2	IO_L122N_Y	T30
2	IO_L123P	T28[4]
2	IO_L123N	R31[5]
2	IO_L124P_Y	T29
2	IO_L124N_Y	U27
2	IO_VREF_L125P_YY	T31
2	IO_L125N_YY	T33
2	IO_L126P_YY	U28

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
7	IO_L324P_Y	L4
7	IO_L325N_YY	J1
7	IO_L325P_YY	L5
7	IO_L326N_YY	J2
7	IO_VREF_L326P_YY	K3
7	IO_L327N_Y	L7
7	IO_L327P_Y	J3
7	IO_L328N_Y	M9[5]
7	IO_L328P_Y	H2[4]
7	IO_L329N_Y	J4
7	IO_VREF_L329P_Y	K6[2]
7	IO_L330N_YY	L8
7	IO_L330P_YY	G2
7	IO_L331N_YY	H3[5]
7	IO_L331P_YY	K7[4]
7	IO_L332N_YY	G3
7	IO_VREF_L332P_YY	J5
7	IO_L333N_Y	L9
7	IO_L333P_Y	H5
7	IO_L334N_Y	J6[5]
7	IO_L334P_Y	H4[4]
7	IO_L335N_Y	G4
7	IO_L335P_Y	K8
7	IO_L336N_YY	J7
7	IO_L336P_YY	F2
7	IO_L337N_YY	F3[5]
7	IO_L337P_YY	L10[4]
7	IO_L338N_Y	E1
7	IO_VREF_L338P_Y_Y	H6
7	IO_L339N_Y	G5
7	IO_L339P_Y	E2
7	IO_L340N	K9
7	IO_L340P	D1
7	IO_L341N_Y	E3

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
7	IO_VREF_L341P_Y	J8
7	IO_L342N_Y	E4
7	IO_L342P_Y	D2
7	IO_L343N_Y	F4
7	IO_L343P_Y	D3
2	CCLK	C31
3	DONE	AM31
NA	DXN	AJ5
NA	DXP	AL5
NA	M0	AK4
NA	M1	AG7
NA	M2	AL3
NA	PROGRAM	AG28
NA	TCK	D5
NA	TDI	C30
2	TDO	K26
NA	TMS	C4
NA	VCCINT	K10
NA	VCCINT	K17
NA	VCCINT	K18
NA	VCCINT	K25
NA	VCCINT	L11
NA	VCCINT	L24
NA	VCCINT	M12
NA	VCCINT	M23
NA	VCCINT	N13
NA	VCCINT	N14
NA	VCCINT	N15
NA	VCCINT	N16
NA	VCCINT	N19
NA	VCCINT	N20
NA	VCCINT	N21

Table 29: **FG1156 Differential Pin Pair Summary: XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
192	4	AK24	AH23	2600 1600 1000	-
193	4	AF22	AP24	3200 2600 2000 1600 1000	VREF
194	4	AL24	AK23	3200 2600 2000 1600 1000	-
195	4	AG22	AN23	3200 1600 1000	-
196	4	AP23	AM23	3200 2000 1000	-
197	4	AH22	AP22	3200 2000 1000	-
198	4	AL23	AF21	3200 2600 1000	-
199	4	AL22	AJ22	3200 2600 2000 1600 1000	-
200	4	AK22	AM22	3200 2600 2000 1600 1000	VREF
201	4	AG21	AJ21	2000 1600	-
202	4	AP21	AE20	3200 2600 1000	-
203	4	AH21	AL21	3200 2600 1000	-
204	4	AN21	AF20	3200	-
205	4	AK21	AP20	3200 2600 2000 1600 1000	-
206	4	AE19	AN20	3200 2600 2000 1600 1000	VREF
207	4	AG20	AL20	3200 1600	-
208	4	AH20	AK20	3200 2000 1000	-
209	4	AN19	AJ20	3200 2000 1000	-
210	4	AF19	AP19	3200 2600	-

Table 29: **FG1156 Differential Pin Pair Summary: XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
211	4	AM19	AH19	3200 2600 2000 1600 1000	-
212	4	AJ19	AP18	3200 2600 2000 1600 1000	VREF
213	4	AF18	AP17	2600 1600 1000	-
214	4	AJ18	AL18	2600 1600 1000	VREF
215	5	AM18	AL17	None	IO_LVDS_DLL
216	5	AH17	AM17	2600 1600 1000	VREF
217	5	AJ17	AG17	2600 1600 1000	-
218	5	AP16	AL16	3200 2600 2000 1600 1000	VREF
219	5	AJ16	AM16	3200 2600 2000 1600 1000	-
220	5	AK16	AP15	3200 2600	-
221	5	AL15	AH16	3200 2000 1000	-
222	5	AN15	AF16	3200 2000 1000	-
223	5	AP14	AE16	3200 1600	-
224	5	AK15	AJ15	3200 2600 2000 1600 1000	VREF
225	5	AH15	AN14	3200 2600 2000 1600 1000	-
226	5	AK14	AG15	3200	-
227	5	AM13	AF15	3200 2600 1000	-
228	5	AG14	AP13	3200 2600 1000	-
229	5	AE14	AE15	2000 1600	-
230	5	AN13	AG13	3200 2600 2000 1600 1000	VREF